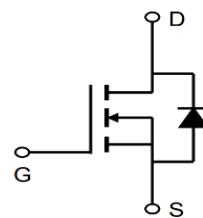
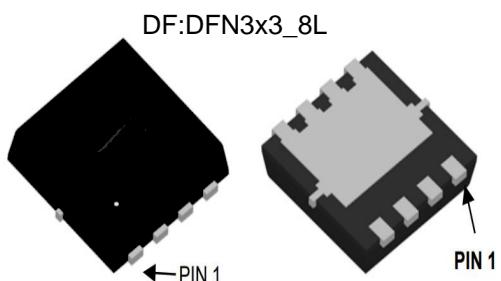
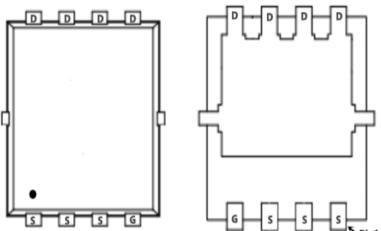


TM0035N03DF
N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low R_{DS(ON)} • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>V_{DS} = 30V I_D = 100A R_{DS(ON)} = 3.5 mΩ (Typ.) @ V_{GS}=10V</p> <p>100% UIS Tested 100% R_g Tested</p> 
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Marking: 100N03D

Absolute Maximum Ratings (T_A=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating		Units
		10s	Steady State	
V _{DS}	Drain-Source Voltage	30		V
V _{GS}	Gate-Source Voltage	±20		V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	100		A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	50		A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	19	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	25	16	A
I _{DM}	Pulsed Drain Current ²	162		A
EAS	Single Pulse Avalanche Energy ³	144.7		mJ
I _{AS}	Avalanche Current	53.8		A
P _D @T _C =25°C	Total Power Dissipation ⁴	62.5		W
P _D @T _A =25°C	Total Power Dissipation ⁴	6	2.42	W
T _{STG}	Storage Temperature Range	-55 to 175		°C
T _J	Operating Junction Temperature Range	-55 to 175		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	25	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	2.4	°C/W

TM0035N03DF
N-Channel Enhancement Mosfet
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}, I_D=30\text{A}$	-	3.5	5.4	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=20\text{A}$	-	5.5	10	
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	2100	-	pF
C_{oss}	Output Capacitance		-	326	-	pF
C_{rss}	Reverse Transfer Capacitance		-	282	-	pF
Q_g	Total Gate Charge	$V_{DS}=15\text{V}, I_D=30\text{A}, V_{GS}=10\text{V}$	-	45	-	nC
Q_{gs}	Gate-Source Charge		-	3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	15	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}, I_D=30\text{A}, R_{GEN}=3\Omega, V_{GS}=10\text{V}$	-	21	-	ns
t_r	Turn-on Rise Time		-	32	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	59	-	ns
t_f	Turn-off Fall Time		-	34	-	ns
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	100	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	$I_F=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	-	200	A
V_{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	15	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	4	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}, V_G=10\text{V}, R_G=25\Omega, L=0.5\text{mH}, I_{AS}=18.4\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

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Figure 1: Output Characteristics

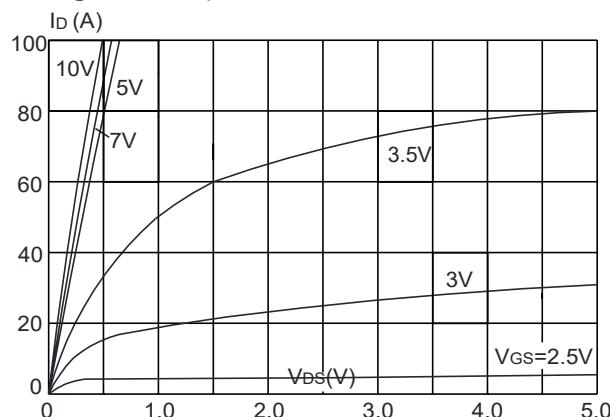


Figure 3: On-resistance vs. Drain Current

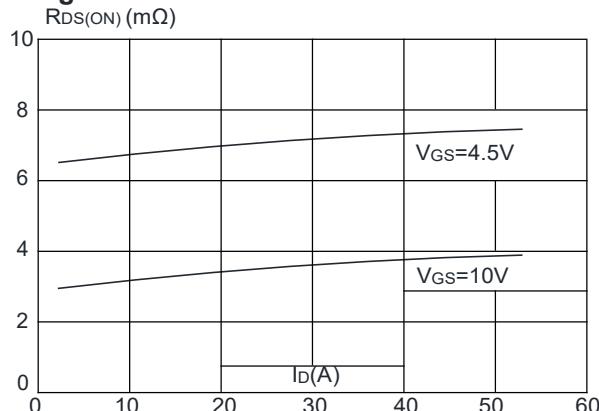


Figure 5: Gate Charge Characteristics

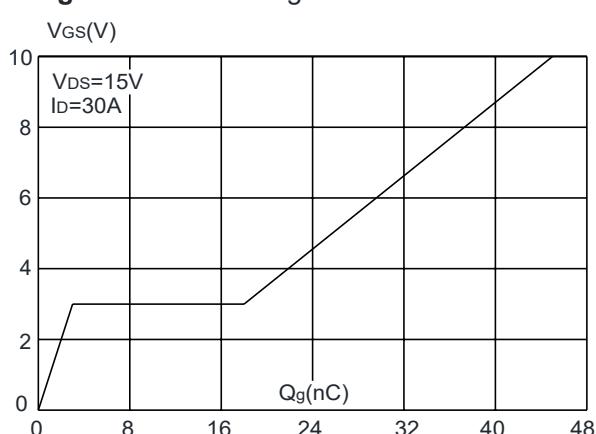


Figure 2: Typical Transfer Characteristics

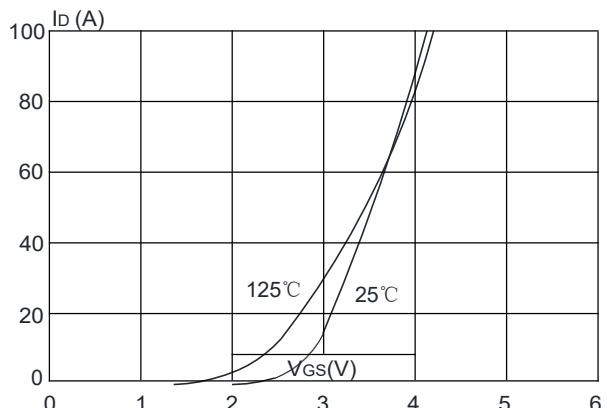


Figure 4: Body Diode Characteristics

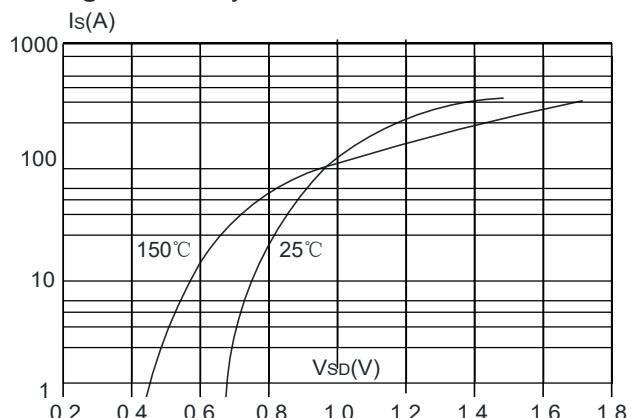
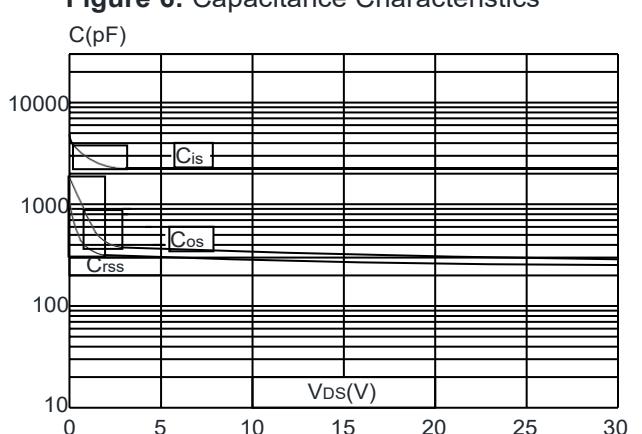


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

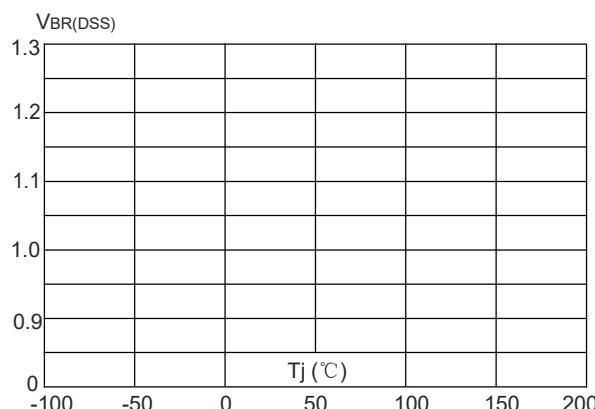


Figure 9: Maximum Safe Operating Area

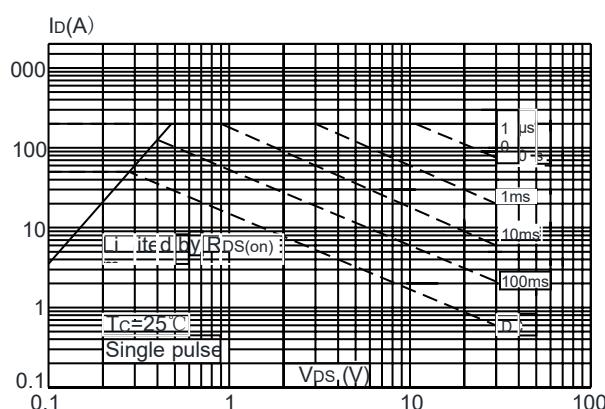


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case (PDFN3.3*3.3-8L)

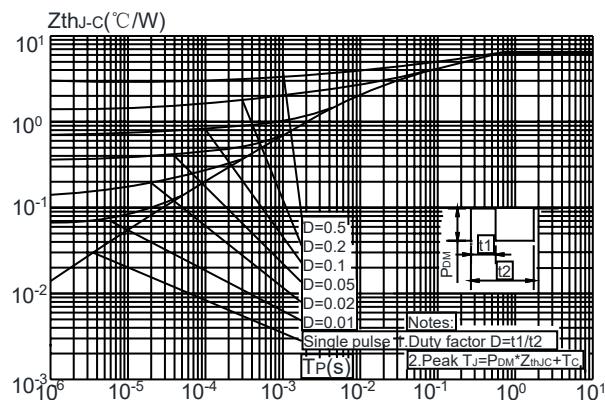


Figure 8: Normalized on Resistance vs. Junction Temperature

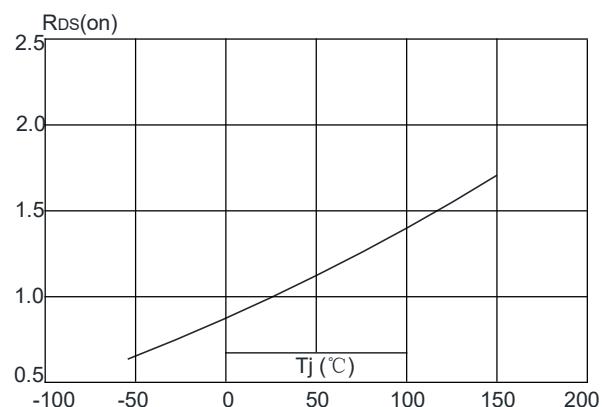
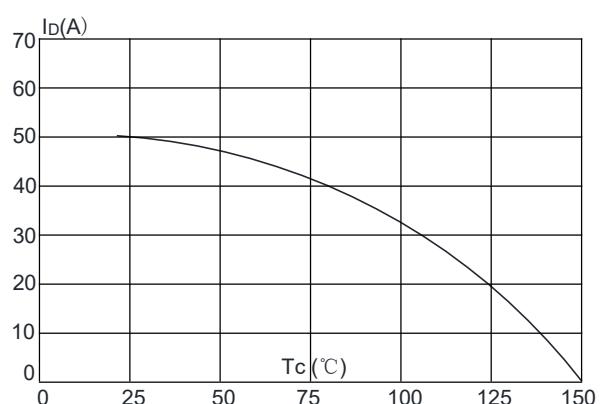


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

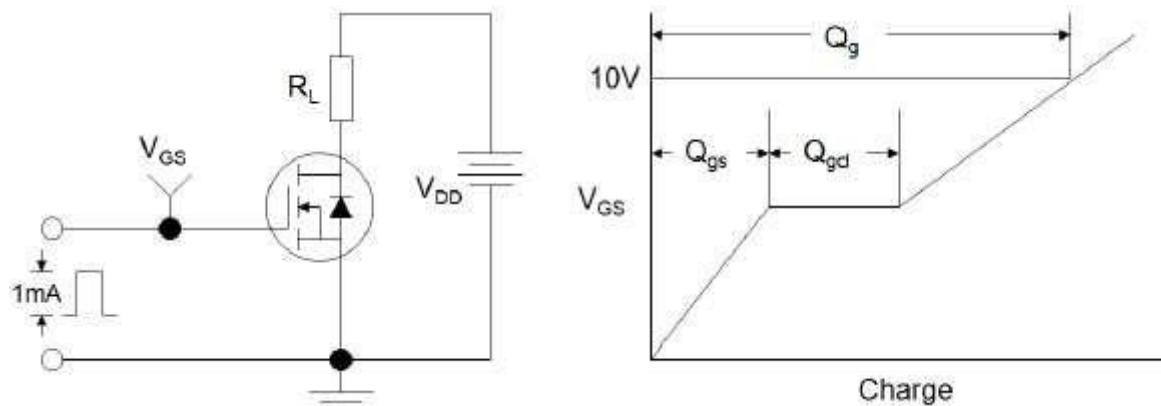


Figure 1: Gate Charge Test Circuit & Waveform

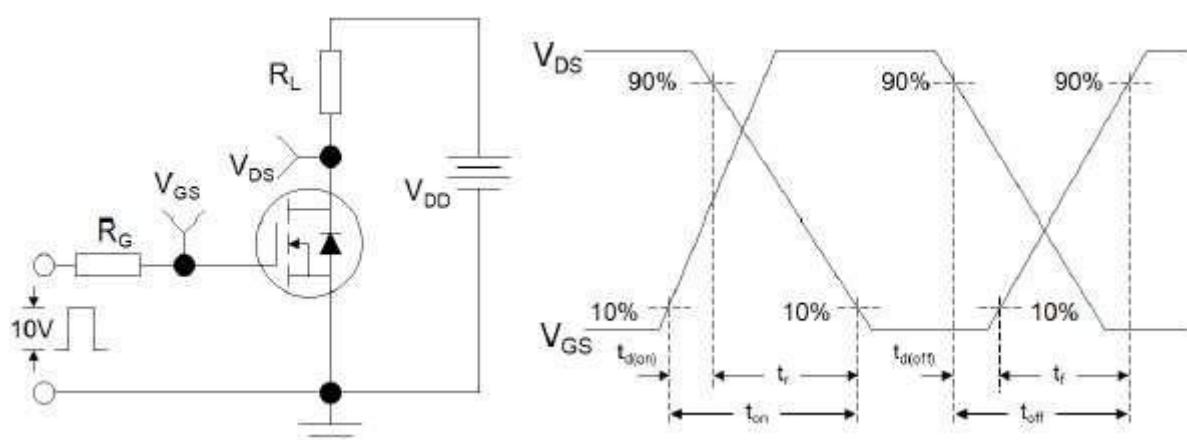


Figure 2: Resistive Switching Test Circuit & Waveforms

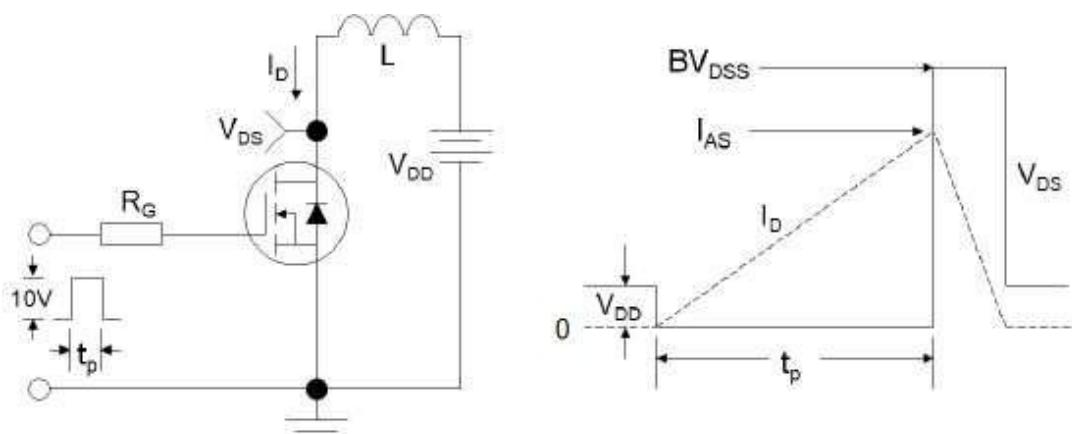
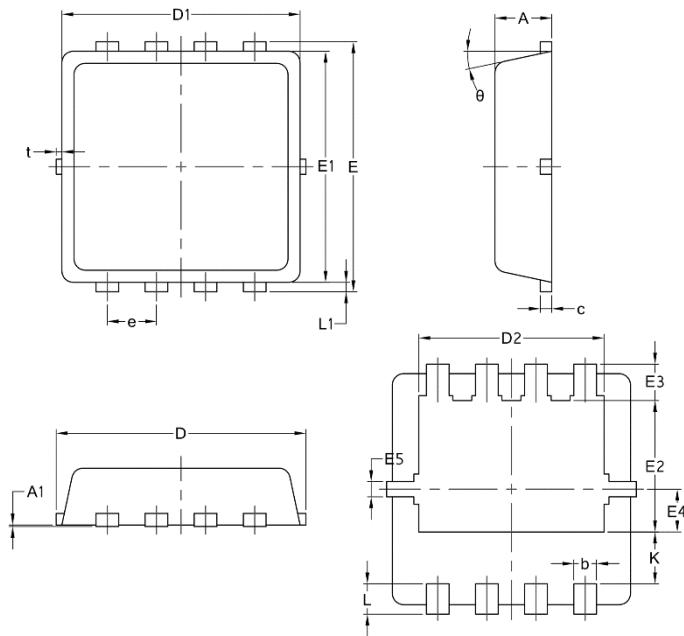


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data: DFN3x3-8L



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14